POLYFUSE[®] Resettable PTCs

Surface Mount > 250S Series

RoHS @HF 250S Series

Expertise Applied Answers Delivered

Littelfuse®

LE 130

Agency Approvals										
AGENCY	AGENCY FILE NUMBER									
c SN° us	E183209									

Description

The 250S High Voltage Radial device is a Polymer-based PTC suitable to protect telephony equipment against lightining and power cross strikes. The 250S Series is fully compatible with telecommunications standards, and is offered in horizontal and new vertical surface mount package.

Features

- RoHS Compliant, Directive 2002/95/EC
- Lead-Free & Halogen-Free
- Low resistance
- Compatible with telecom standards
- Helps meets ITU K.20, K.21/Telcordia standards
- Excellent solder joint inspectability
- High voltage

Applications

- Customer Premises Equipment (CPE)
- Central Office (CO)/ telecom centers
- LAN/WAN equipment
- Access equipment

Electrical Characteristics

Part Number	Device Mounting	 hold	ا _{trip}	V _{max}	ا _{max}	P _d typ.	Time to Trip at 1A		R	lesistand	Agency Approvals	
	Layout	(A)	(A)	(V _{int} /V _{op})	(A)	(₩)	Typical (Sec.)	Maximum (Sec.)	R _{min} (Ω)	R _{max} (Ω)	R _{1max} (Ω)	c 🏊 us
250S130		0.13	0.26	250/60	3	1.2	0.9	4.0	4	13	20	-
250S130-RA	Horizontal	0.13	0.26	250/60	3	1.2	1.4	4.0	6.5	10	15	-
250S130-RB	Horizontai	0.13	0.26	250/60	3	1.2	0.7	4.0	9	13	20	-
250S130-RC		0.13	0.26	250/60	3	1.2	1.1	4.0	7	11	17	-
250S130V	Vertical	0.13	0.26	250/60	3	1.2	2.0	4.0	4	13	20	-

I $_{\rm hold}$ = Hold current: maximum current device will pass without tripping in 23°C still air.

I $_{\rm trip}$ = Trip current: minimum current at which the device will trip in 23°C still air.

 $V_{\rm int}$ = Maximum voltage the device can withstand without damage at rated current (I max) $V_{\rm or}$ = The device regular operation voltage

I $_{max}$ = Maximum fault current device can withstand without damage at rated voltage (V $_{max}$)

P $_{\rm d}$ = Power dissipated from device when in the tripped state at 23°C still air.

R $_{min}$ = Minimum resistance of device in initial (un-soldered) state.

R $_{max}$ = Maximum resistance of device in initial (un-soldered) state.

R _{tmax} = Maximum resistance of device at 20°C measured one hour after tripping.

 $\ensuremath{\textbf{Caution:}}$ Operation beyond the specified rating may result in damage and possible arcing and flame.

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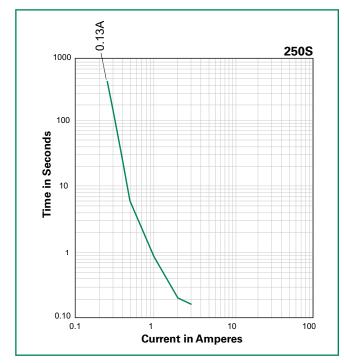
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Temperature Rerating

	Ambient Operation Temperature										
	-40°C	-20°C	0°C	23°C	40°C	50°C	60°C	70°C	85°C		
Part Number	Hold Current (A)										
250S130	0.21	0.19	0.17	0.13	0.11	0.10	0.09	0.07	0.05		

Average Time Current Curves



The average time current curves and Temperature Rerating curve performance is affected by a number or variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Temperature Rerating Curve



Agency Specification Selection Guide For Telecom and Networking Applications

Product	Lightning	Power Cross					
250S130 250S130V 250S130-RA 250S130-RB 250S130-RC	ITU K.20/21/45 – 1.5kV 10/700μs	ITU K.20/21/45 – 230Vac, 10Ω					

Protection Application Guide

Region/ Specification	Application	Device Selection
South America/ Asia/Europe ITU K.45	Access network equipment Remote terminal Repeaters WAN equipment Cross –connect	250S130 250S130V 250S130-RA 250S130-RB 250S130-RC
South America/ Asia/Europe ITU K.21	Customer and IT equipment Analog modems ADSL, xDSL Phone sets, PBX systems Internet appliances POS terminals	250S130 250S130V 250S130-RA 250S130-RB 250S130-RC
South America/ Asia/Europe ITU K.20	Central Office POTS/ISDN linecards T1/E1/J1 linecards ADSL/VDSL splitters CSU/DSU	250S130 250S130V 250S130-RA 250S130-RB 250S130-RC

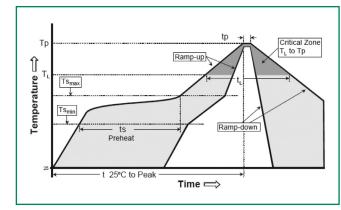


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Soldering Parameters

Profile Feature		Pb-Free Assembly			
Average Ramp-Up	Rate ($T_{S(max)}$ to T_{P})	3°C/second max			
	Temperature Min (T _{s(min)})	150°C			
Pre Heat:	Temperature Max (T _{s(max)})	200°C			
	Time (Min to Max) (t _s)	60 – 180 secs			
Time Maintained	Temperature (T_L)	217°C			
Above:	Temperature (t _L)	60 – 150 seconds			
Peak / Classificatio	on Temperature (T _P)	260 ^{+0/-5} °C			
Time within 5°C o Temperature (t _p)	f actual peak	20 – 40 seconds			
Ramp-down Rate	6°C/second max				
Time 25°C to peak	Temperature (T _P)	8 minutes Max.			



- All temperature refer to topside of the package, measured on the package body surface
- If reflow temperature exceeds the recommended profile, devices may not meet the performance requirements
- Recommended reflow methods: IR, vapor phase oven, hot air oven, $\mathrm{N_2}$ environment for lead
- Recommended maximum paste thickness is 0.25mm (0.010inch)
- Devices can be cleaned using standard industry methods and solvents
- Devices can be reworked using the standard industry practices

Physical Specifications									
Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin(Sn))								
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/ J-STD-002 Category 3.								

Environmental Specifications

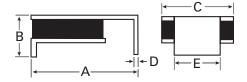
Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C -/+10°C
Passive Aging	+85°C, 1000 hours
Humidity Aging	+85°C, 85%,R.H.,1000 hours
Thermal Shock	MIL–STD–202F, Method 107G +125°C to -55°C 10 times
Solvent Resistance	MIL–STD–202, Method 215F
Moisture Sensitivity Level	Level 1, J-STD-020C

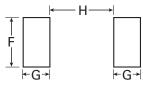
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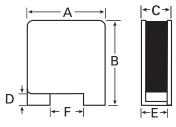
Dimensions

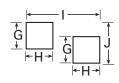




Soldering Pad Layout

Part	ļ	4		В	(C	[)	E			F		G		Н	
Number	Inch	mm	Inch	mm	Inch	mm	Inch	mm	Inch	mm	Material	Inch	mm	Inch	mm	Inch	mm
Number	Max.	Max.	Max.	Max.		Max.	Max.	Max.	Max.	Max.	Max.						
250S130	0.37	9.4	0.15	3.7	0.29	7.4	0.016	0.4	0.15	3.8	Sn/Ni/Cu	0.18	4.6	0.07	1.8	0.24	6.1
250S130-RA	0.37	9.4	0.15	3.7	0.29	7.4	0.016	0.4	0.15	3.8	Sn/Ni/Cu	0.18	4.6	0.07	1.8	0.24	6.1
250S130-RB	0.37	9.4	0.15	3.7	0.29	7.4	0.016	0.4	0.15	3.8	Sn/Ni/Cu	0.18	4.6	0.07	1.8	0.24	6.1
250S130-RC	0.37	9.4	0.15	3.7	0.29	7.4	0.016	0.4	0.15	3.8	Sn/Ni/Cu	0.18	4.6	0.07	1.8	0.24	6.1

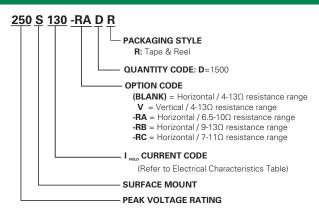




Soldering Pad Layout

Part	ŀ	4		З	(С	E)	E	-		F		(3	ŀ	ł				J
Number	Inch	mm	Material	Inch	mm	Inch	mm	Inch	mm	Inch	mm										
Number	Max.		Max.																		
250S130V	.24	6.1	.27	6.9	.13	3.2	.04	1.0	.07	1.9	.09	2.3	Sn/Ni/Cu	.09	2.3	.09	2.4	.25	6.4	.14	3.43

Part Ordering Number System



Packaging

Гаскаушу						
Part Number	Ordering Number	l _{hold} (A)	I _{hold} Code	Packaging Option	Quantity	Quantity & Packaging Code
250S130	250S130DR	0.13	130	Tape and Reel	1500	DR
250S130V	250S130VDR	0.13	130	Tape and Reel	1500	DR
250S130-RA	250S130-RADR	0.13	130	Tape and Reel	1500	DR
250S130-RB	250S130-RBDR	0.13	130	Tape and Reel	1500	DR
250S130-RC	250S130-RCDR	0.13	130	Tape and Reel	1500	DR



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Tape and Reel Specifications

	SPECIFICATIONS:		IMENSIONS:
-	IA-481-1 (mm)	EIA-4	81-1 (mm)
W	16 +/-0.30	н	22.4 +/-0.05
F	7.5 +/-0.05	w	16.4 .0 +0/+2
E ₁	1.75 +/-0.10	D	Ø60+0.5
D ₀	1.5 +/-0.05	F	Ø13.0+/-0.2
D ₁	1.00(MIN)	С	Ø340+/-1.0
P ₀	4.00 +/-0.10	H ₁	11+/-0.5
P ₁	12.00 +/-0.10	W ₁	2.2+/-0.5
P ₂	2.00 +/-0.05	W ₂	3.0+0.5
A ₀	6.9 +/-0.10	W ₃	4.0+0.5
B	9.6 +/-0.10	W_4	5.5+0.5
T _{max}	0.4 +/-0.10		
κ	3.4 +/-0.15		
Leader Min.	300		
Trailer Min.	300		

Tape and Reel Diagram

